Abstracts

Modeling millimeter-wave IC behavior for flipped-chip mounting schemes

R.W. Jackson and R. Ito. "Modeling millimeter-wave IC behavior for flipped-chip mounting schemes." 1997 Transactions on Microwave Theory and Techniques 45.10 (Oct. 1997, Part II [T-MTT] (Special Issue on Interconnects and Packaging)): 1919-1925.

A circuit topology is presented for modeling flipped-chip-mounted monolithic microwave integrated circuits (MMIC's) at microwave frequencies. The proposed topology especially models the loss of isolation due to the flipped-chip structure. Both coplanar and microstrip flipped chips are circuit modeled and their results compared to full numerical simulations and to scale-model measurements. Both measurements and numerical modeling show resonances in the millimeter-wave range.

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